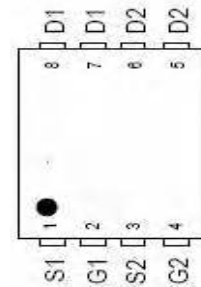
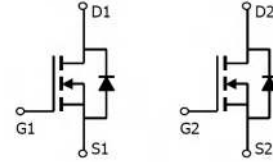


## Dual N-Channel Enhancement Mosfet

### Features

- 60V,30A  
 $R_{DS(on)} < 30m\Omega @ V_{GS}=10V$  TYP:22m $\Omega$   
 $R_{DS(on)} < 42m\Omega @ V_{GS}=4.5V$  TYP:29m $\Omega$
- Advanced Trench Technology
- Lead free product is acquired
- Excellent  $R_{DS(on)}$ , and Low Gate Charge



pin assignment

### Applications

- Load Switch
- PWM Application
- Power Management
- Halogen-free

### Package Marking and Ordering Information

Device Marking	Device	Package	Packaging Code	Reel Size	Quantity(Pcs)	Carton(Pcs)
D30N60	RMD30N60D3	DFN3X3	-W	13inch	5000	80000

### ABSOLUTE MAXIMUM RATINGS ( $T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_c=25^{\circ}\text{C}$ )	$I_D$	30	A
Continuous Drain Current ( $T_c=100^{\circ}\text{C}$ )	$I_D$	20	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	120	A
Drain Power Dissipation	$P_D$	35	W
Single Pulsed Avalanche Energy <sup>(2)</sup>	$E_{AS}$	23	mJ
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3.6	$^{\circ}\text{C}/\text{W}$
Junction Temperature	$T_J$	-55~ +150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^{\circ}\text{C}$

#### Notes:

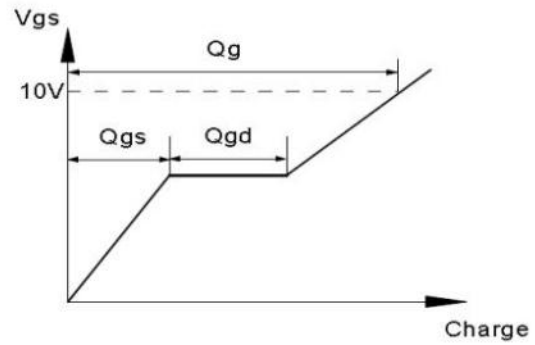
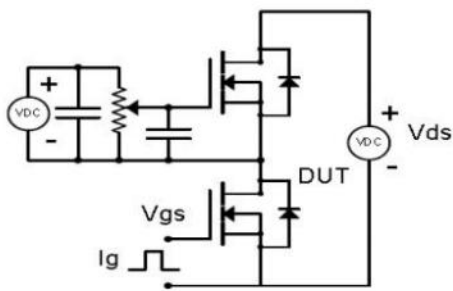
- 1) Repetitive Rating: pulse width limited by maximum junction temperature
- 2) EAS condition :  $T_J=25^{\circ}\text{C}$ ,  $V_{DD}=30\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=9.6\text{A}$

## MOSFET ELECTRICAL CHARACTERISTICS( $T_J=25^{\circ}\text{C}$ unless otherwise noted)

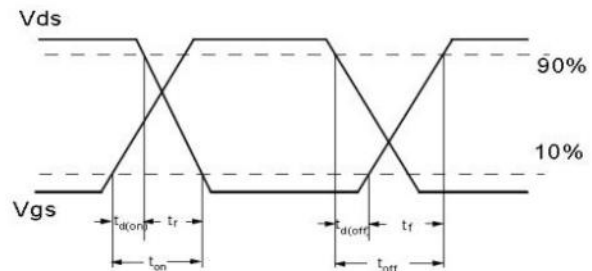
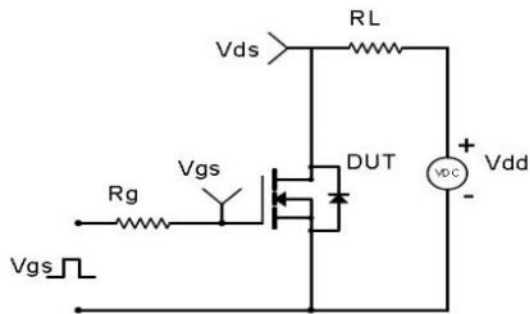
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 60V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 15A$	-	22	30	m $\Omega$
		$V_{GS} = 4.5V, I_D = 10A$	-	29	42	m $\Omega$
<b>Dynamic characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 30V, V_{GS} = 0V, f = 1MHz$	-	1488	-	pF
Output Capacitance	$C_{oss}$		-	72	-	
Reverse Transfer Capacitance	$C_{rss}$		-	64	-	
<b>Switching characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 30V, I_D = 15A, R_G = 1.8\Omega, V_{GS} = 10V$	-	7.5	-	nS
Turn-on rise time	$t_r$		-	21	-	
Turn-off delay time	$t_{d(off)}$		-	16	-	
Turn-off fall time	$t_f$		-	23.5	-	
Total Gate Charge	Qg	$V_{DS} = 30V, I_D = 15A, V_{GS} = 10V$	-	25	-	nC
Gate-Source Charge	Qgs		-	4.5	-	
Gate-Drain Charge	Qgd		-	6.5	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage	$V_{SD}$	$T_J = 25^{\circ}\text{C}, V_{GS} = 0V, I_S = 15A$	-	0.8	1.2	V
Diode Forward current	$I_S$	$T_C = 25^{\circ}\text{C}$	-	-	30	A
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25^{\circ}\text{C}, I_F = 15A, di/dt = 100A/\mu s$	-	29	-	nS
Body Diode Reverse Recovery Charge	Qrr		-	45	-	nC

## Test Circuit & Waveform

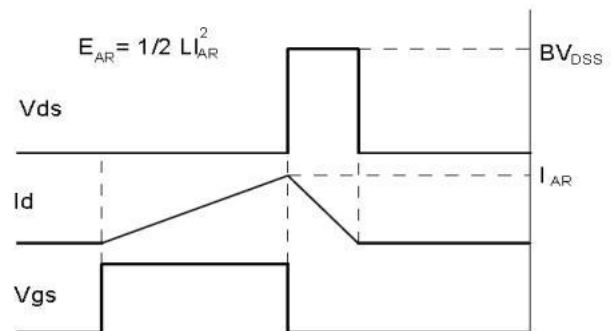
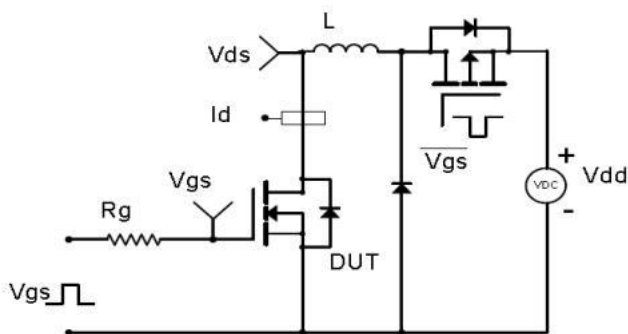
### Gate Charge Test Circuit & Waveform



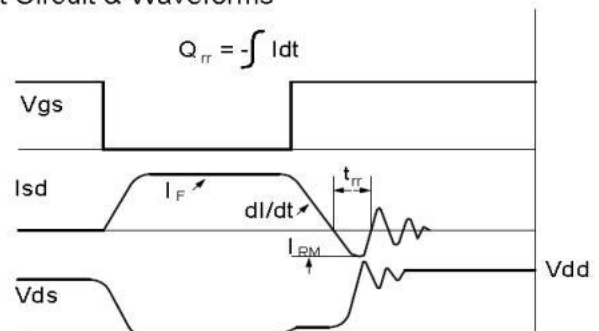
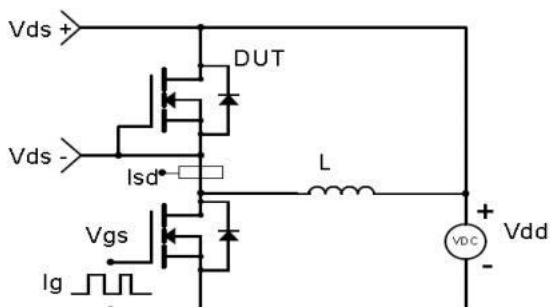
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

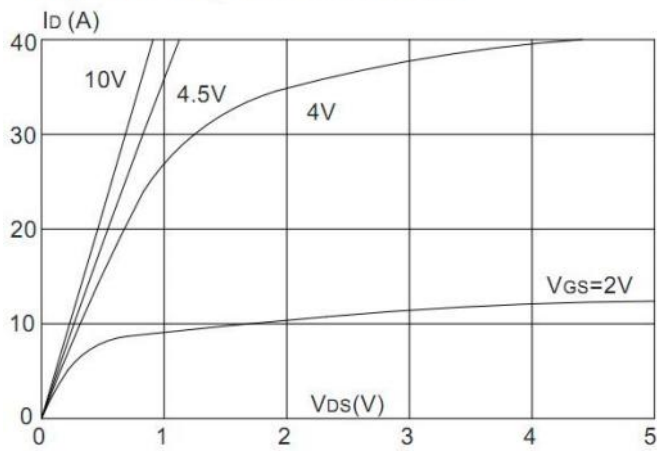


### Diode Recovery Test Circuit & Waveforms

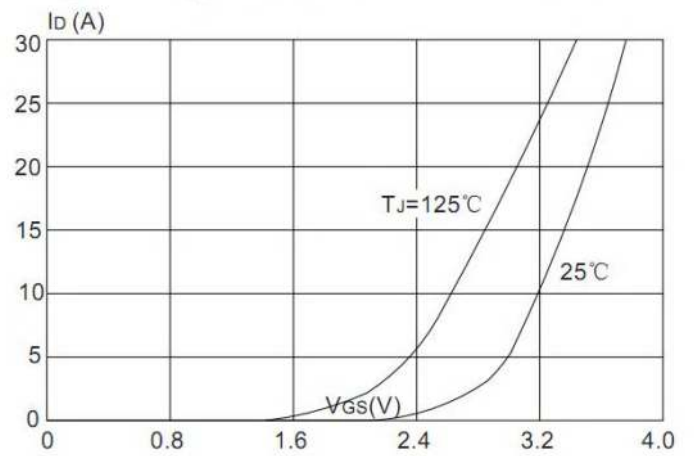


# RATING AND CHARACTERISTICS CURVES (RMD30N60D3)

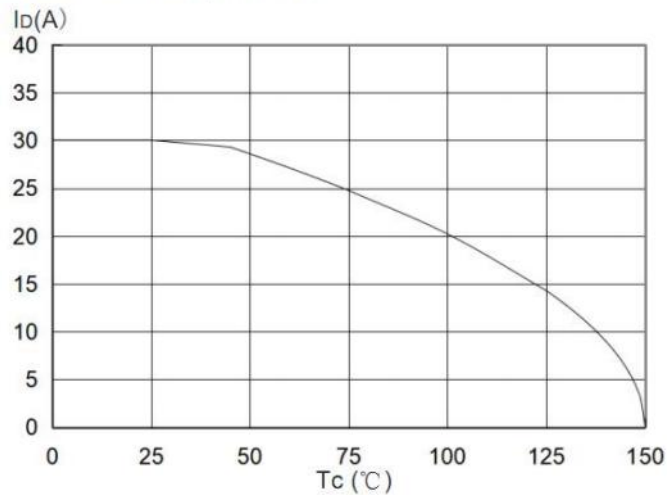
**Figure 1: Output Characteristics**



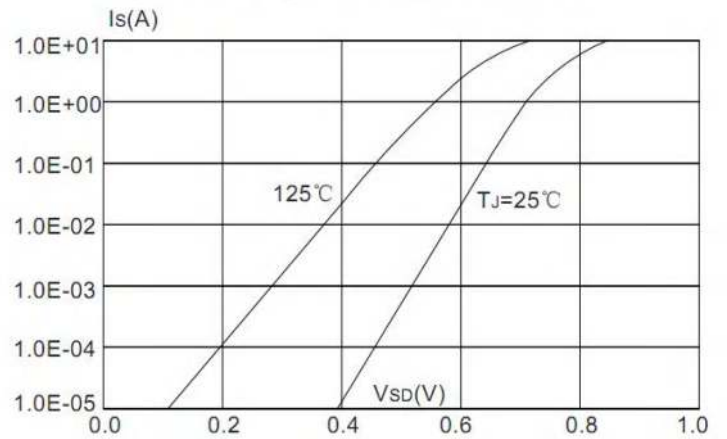
**Figure 2: Typical Transfer Characteristics**



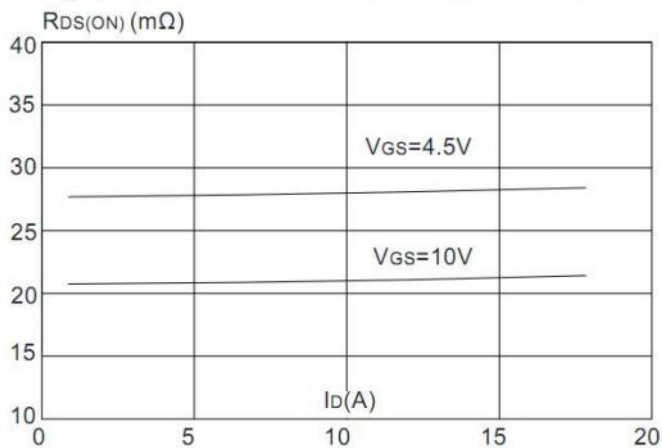
**Figure 3: Maximum Continuous Drain Current vs. Case Temperature**



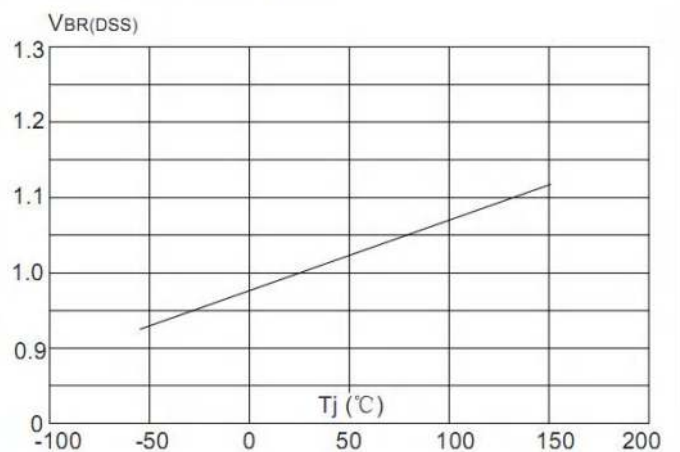
**Figure 4: Body Diode Characteristics**



**Figure 5: On-resistance vs. Drain Current**

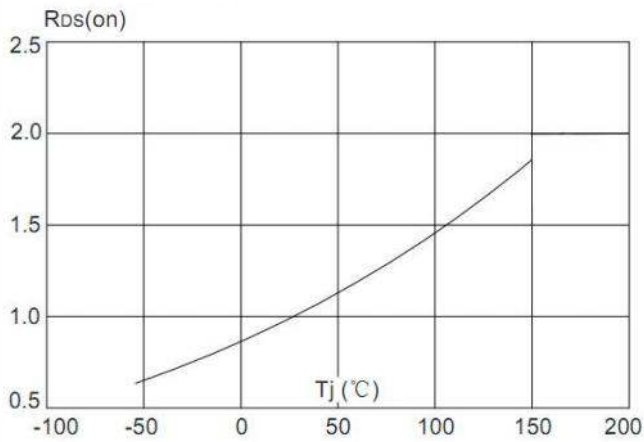


**Figure 6: Normalized Breakdown Voltage vs. Junction Temperature**

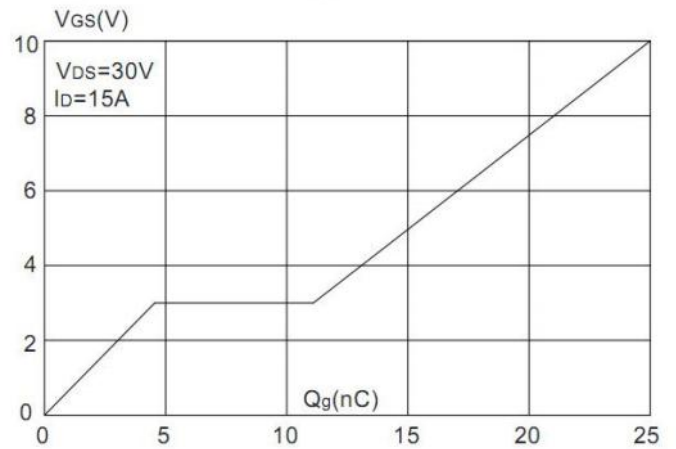


# RATING AND CHARACTERISTICS CURVES (RMD30N60D3)

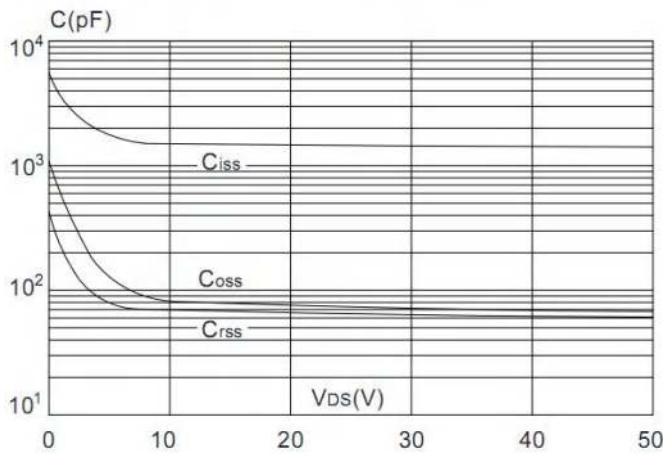
**Figure 7:** Normalized on Resistance vs. Junction Temperature



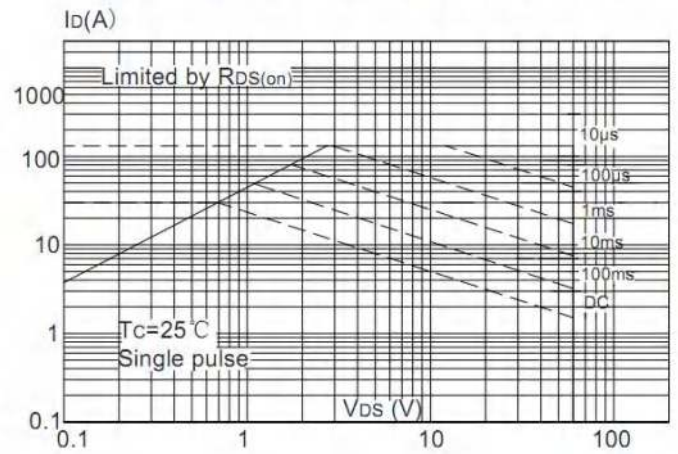
**Figure 8:** Gate Charge Characteristics



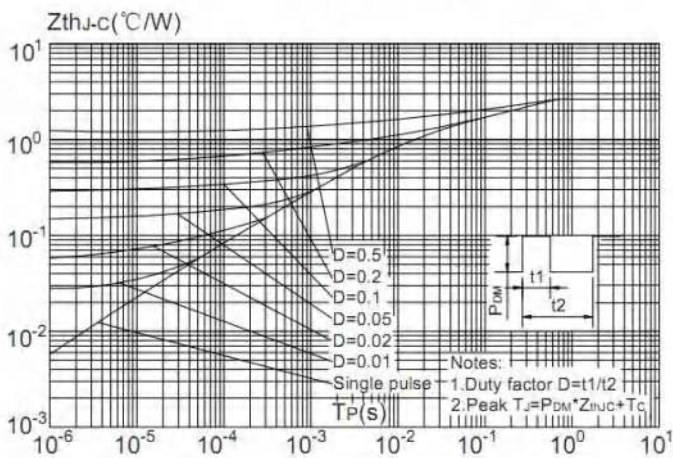
**Figure 9:** Capacitance Characteristics



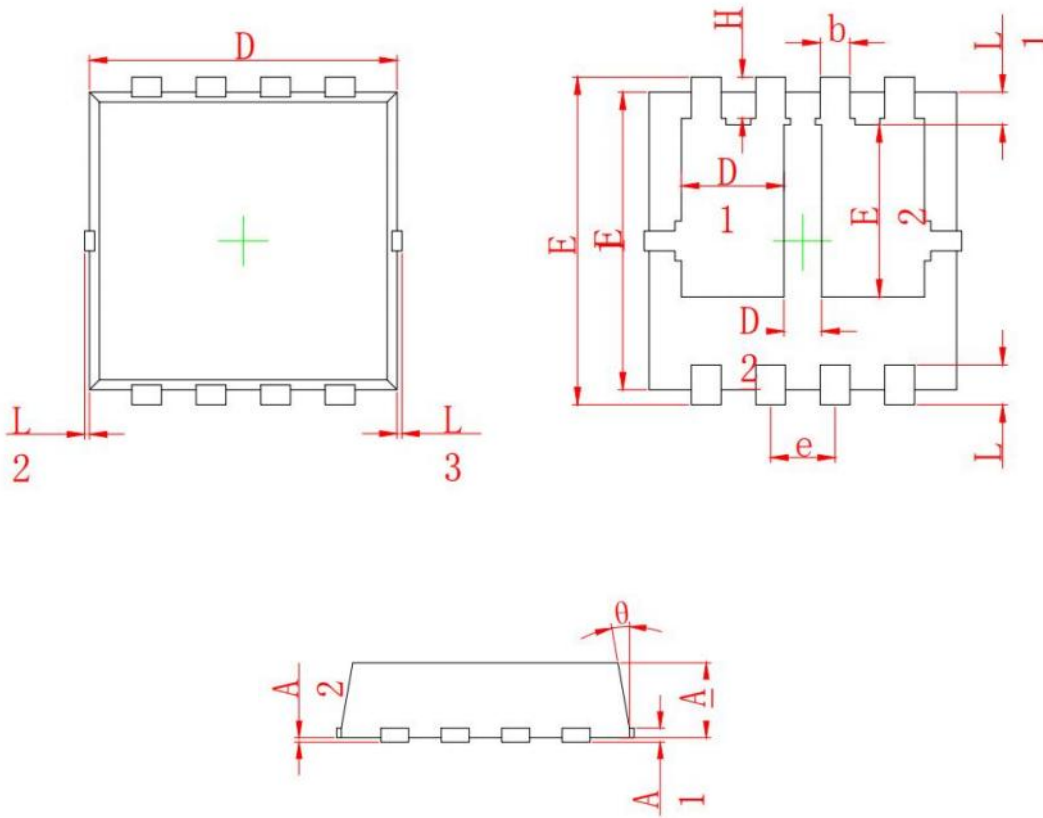
**Figure 10:** Maximum Safe Operating Area



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



# DFN3X3 Package Information

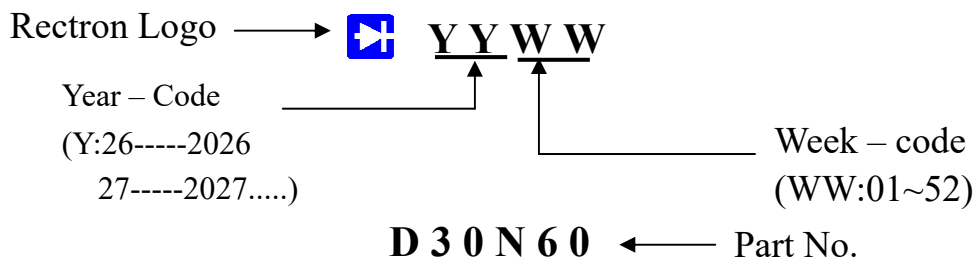


SYMBOL	MILLIMETER	
	MIN	MAX
A	0.700	0.900
A1	0.152 REF.	
A2	0~0.05	
D	3.000	3.200
D1	0.935	1.135
D2	0.280	0.480
E	2.900	3.100
E1	3.150	3.450
E2	1.535	1.935
b	0.200	0.400
e	0.550	0.750
L	0.300	0.500
L1	0.180	0.480
L2	0~0.100	
L3	0~0.100	
H	0.315	0.515
$\theta$	8°	12°



# RECTRON

## Marking on the body



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